



# Material Composition Declaration

## EPC2036

Company Name	Efficient Power Conversion (EPC)	Issue Date:	5/4/2016
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	1.3 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight (mg)	Mass (%)	Sum (%)	Mass (ppm)
Chip	Silicon	7440-21-3	1.1602	87.83	90.41	878330
	Silicon oxide	7631-86-9	0.0050	0.38		3810
	Silicon nitride	12033-89-5	0.0017	0.13		1279
	Gallium nitride	25617-97-4	0.0060	0.45		4532
	Aluminum	7429-90-5	0.0095	0.72		7178
	Aluminum nitride	24304-00-5	0.0014	0.11		1094
	Titanium	7440-32-6	0.0002	0.02		159
	Titanium nitride	25583-20-4	0.0008	0.06		639
	Copper	7440-50-8	0.0003	0.02		239
	Tungsten	7440-33-7	0.0003	0.03		254
	Polyimide		0.0087	0.66		6576
Under Bump Metal	Titanium	7440-32-6	0.0001	0.01	0.16	60
	Nickel	7440-02-0	0.0000	0.00		0
	Vanadium	7440-62-2	0.0000	0.00		0
	Copper	7440-50-8	0.0020	0.15		1522
Solder Bar	Tin	7440-31-5	0.1190	9.01	9.43	90081
	Silver	7440-22-4	0.0050	0.38		3773
	Copper	7440-50-8	0.0006	0.05		472
Sum in total:			1.3	100.00	100	1000000

**Note:**

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.